

INTERCONNECTS

SERIES 850, 851, 852, 853 • 1,27 GRID HEADERS AND SOCKETS • SINGLE AND DOUBLE ROW STRIPS

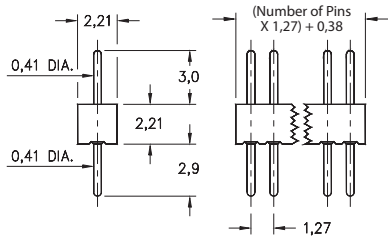


FIG. 1

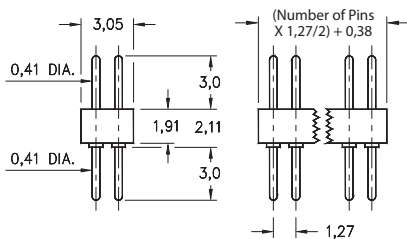


FIG. 2

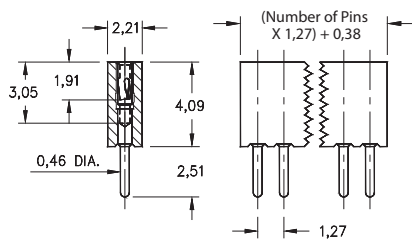


FIG. 3

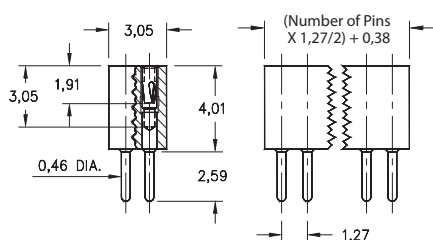


FIG. 4

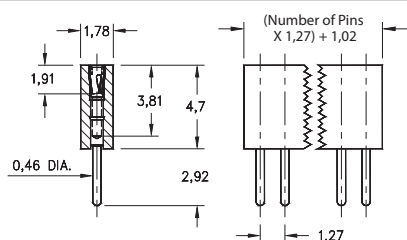


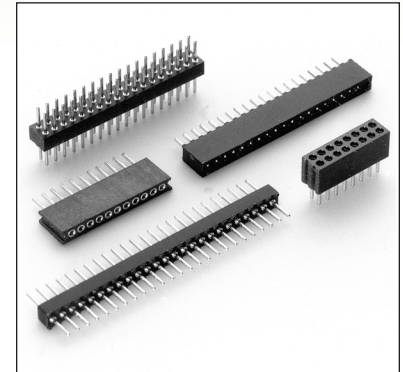
FIG. 5

• Series 850, 851, 852, 853 single and double row interconnects have 1,27 pin spacing and permit board stacking as low as 6,3

• Pin headers have 0,41 dia. pins (MM #4006-0) See page 208 for details

• MM #0467 and MM #4890 receptacles use Hi-Rel, 3-finger BeCu #11 contact rated at 3 amps. (#11 contact accepts pin diameters from 0,38 - 0,51). See pages 158 and 160 for details

• Insulators are high temperature thermoplastic, suitable for all soldering operations



ORDERING INFORMATION

FIG. 1	Series 850...001 Single Row 2,21 Profile Pin Header		
	850-XX-0-10-001000 Specify number of pins 01-50		
FIG. 2	Series 852...001 Double Row 2,11 Profile Pin Header		
	852-XX--10-001000 Specify number of pins 002-100		
RoHS-2 2011/65/EU XX=Plating Code See Below For Electrical, Mechanical & Enviromental Data, See page 264			
SPECIFY PLATING CODE XX= 10 90 40			
Pin Plating 0,25µm Au 5,08µm Sn/Pb 5,08µm Sn			
FIG. 3	Series 851...001 Single Row 4,09 Profile Socket		
	851-XX-0-10-001000 Specify number of pins 01-50		
FIG. 4	Series 853...001 Double Row 4,09 Profile Socket		
	853-XX--10-001000 Specify number of pins 002-100		
FIG. 5	Series 851...002 Single Row 4,7 Profile Socket		
	851-XX-0-10-002000 Specify number of pins 01-77		
RoHS-2 2011/65/EU XX=Plating Code See Below For Electrical, Mechanical & Enviromental Data, See page 264			
SPECIFY PLATING CODE XX= 91 93 99 41 43			
Sleeve (Pin) 5,08µm Sn/Pb 5,08µm Sn/Pb 5,08µm Sn/Pb 5,08µm Sn 5,08µm Sn			
Contact (Clip) 0,25µm Au 0,76µm Au 2,54µm Sn/Pb 0,25µm Au 0,76µm Au			